

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently amended) A device for ~~the storage~~ storing of at least one of a solid[[and]], a liquid [[and]] or a gaseous objects object, the device having in particular one of medicines and food, with at least one compartment ~~which~~ configured to contains contain at least one object, wherein ~~in that one of the filling~~ placing the object in the compartment [[and]] or emptying of the compartment removing the object from the compartment triggers an electrically readable signal .
2. (Currently amended) The device as claimed in claim 1, wherein the compartment is mechanically changeable for ~~one of~~ removal of the object from the compartment [[and for]] or filling with placing the object in the compartment, and an electrically readable signal is generated ~~when there is a mechanical change of the compartment~~.
3. (Currently amended) The device as claimed in claim 2, wherein ~~integrated in~~ the device [[is]] comprises[[(:)] an electrical data memory with including at least one memory cell ~~which is respectively assigned to~~ [[a]] the compartment and ~~which adopts a different memory value when there is a mechanical change of the compartment~~.
4. (Currently amended) The device as claimed in claim 27 [[3]], wherein ~~also integrated in~~ the device [[are]] further comprises[[(:)] evaluation electronics for reading the memory value from the electrical data memory.
5. (Currently amended) The device as claimed in claim 3, wherein the compartment ~~forms part~~ is electrically coupled to ~~of~~ the memory cell.

6. (Currently amended) The device as claimed in claim 5, wherein the compartment ~~[[has]]~~ includes an interconnect~~which, the interconnect being~~ [[is]] part of the memory cell, and ~~the interconnect~~ [[is]] being configured to be substantially destroyed after ~~when there is~~ [[a]] the mechanical change of the compartment,~~whereby the memory cell adopts a~~ different value.
7. (Currently amended) The device as claimed in claim 5, wherein the compartment forms a capacitance, the capacitance being ~~and the capacitance~~ [[is]] substantially changed after ~~when there is~~ [[a]] the mechanical change of the compartment,~~whereby the memory cell~~ adopts a different value.
8. (Currently amended) The device as claimed in claim 5, wherein the compartment forms an inductance, the inductance being ~~and the inductance~~ substantially changed after ~~changes~~ when there is [[a]] the mechanical change of the compartment,~~whereby the memory cell~~ adopts a different value.
9. (Currently amended) The device as claimed in claim 4, wherein the evaluation electronics ~~have~~ comprise a shift register for reading the memory value from the electrical data memory.
10. (Currently amended) The device as claimed in claim 4, wherein the evaluation electronics ~~have~~ comprise [[two]] a terminal contacts contact for [[the]] voltage and a terminal contact for serial data transmission.
11. (Currently amended) The device as claimed in claim 4, further comprising:
an interface of the evaluation electronics, the interface having one or more
contacts for providing data transmission; and

an external reader configured to provide data transmission through the one or more contacts of the interface. ~~wherein the evaluation electronics have an interface with or without contacts for the data transmission between the evaluation electronics and an external reader.~~

12. (Currently amended) The device as claimed in claim 4, wherein the evaluation electronics have comprise a timer configured to generate information indicative of the time ~~and store the time~~ at which ~~[[a]]~~ the compartment ~~[[was]]~~ is mechanically changed.
13. (Currently amended) The device as claimed in claim ~~[[3]]~~ 6, wherein at least one of one the memory cell ~~and interconnects and, the interconnect or components~~ of the evaluation electronics are integrated in ~~[[the]]~~ a substrate of the device.
14. (Currently amended) The device as claimed in claim 13, wherein the electrical data memory is ~~formed as an inherent~~ a write once read only memory ~~WORM~~ memory integrated in the substrate.
15. (Currently amended) The device as claimed in claim 13, wherein at least one of the data memory ~~and interconnects and, the interconnect or components~~ of the evaluation electronics are at least partly formed as ~~elements~~ of polymer electronics.
16. (Currently amended) The device as claimed in claim 13, wherein the device ~~has~~ includes an assembly of layers, ~~and~~ at least one of the layers of the assembly of layers being configured to be used ~~used~~ for forming an electrical function.
17. (Currently amended) The device as claimed in claim 16, wherein at least one of active electrical components ~~[[and]]~~ or passive electrical components are integrated in the

assembly of layers, ~~such as transistors, diodes, capacitors, inductors or resistors as well as circuits formed from them.~~

18. (Currently amended) The device as claimed in claim 13, wherein the substrate ~~has~~ includes an aluminum layer, ~~which forms the aluminium layer including the electrical lines interconnect.~~
19. (Currently amended) The device as claimed in claim 13, wherein the substrate includes has printed-on organic compounds, ~~which for realization of~~ realize the ~~interconnects~~ interconnect.
20. (Currently amended) The device as claimed in claim 13, wherein the device ~~represents or has~~ is a pack, the pack having one or more compartments formed therein ~~which forms the compartments,~~ and having the data memory and the evaluation electronics ~~[[are]]~~ integrated in ~~[[the]]~~ a substrate of the pack.
21. (Currently amended) The device as claimed in claim 20, wherein the substrate of the pack ~~serves as~~ is configured to be a carrier for at least one of ~~electrical lines~~ the interconnect ~~[[and]]~~ or the evaluation electronics.
22. (Currently amended) The device as claimed in claim 20, wherein the evaluation electronics are integrated in a chip ~~with~~ having an integrated voltage source, the chip being ~~that is~~ attached to the pack.
23. (Previously Presented) The device as claimed in claim 1, wherein the device is a blister pack.

24. (Currently amended) The device as claimed in claim 23, wherein the blister pack includes one or more blisters, each of the one or more blisters being configured to communicate with a blister forms part of a memory cell.
25. (Cancelled)
26. (New) The device as claimed in claim 2, further comprising the device being configured to generate an electrically readable signal after there is a mechanical change of the compartment.
27. (New) The device as claimed in claim 3, wherein the memory cell adopts a memory value after the mechanical change of the compartment.
28. (New) The device as claimed in claim 4, further comprising:
an interface of the evaluation electronics, the interface being configured to provide data transmission; and
an external reader configured to provide data transmission with the interface.
29. (New) The device as claimed in claim 4, further comprising the evaluation electronics being configured to store the time at which the compartment is mechanically changed.
30. (New) The device as claimed in claim 17, wherein the active electrical components includes at least one of one or more transistors or circuits formed from the one or more transistors, and wherein the passive electrical components includes at least one of one or more diodes, capacitors, inductors or resistors or circuits formed from the one or more diodes, capacitors, inductors or resistors.